

NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.

2) CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)  
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.

3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)

4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)


REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.

5 THIS IS PACKAGED IN TRAY. (40pcs/TRAY)

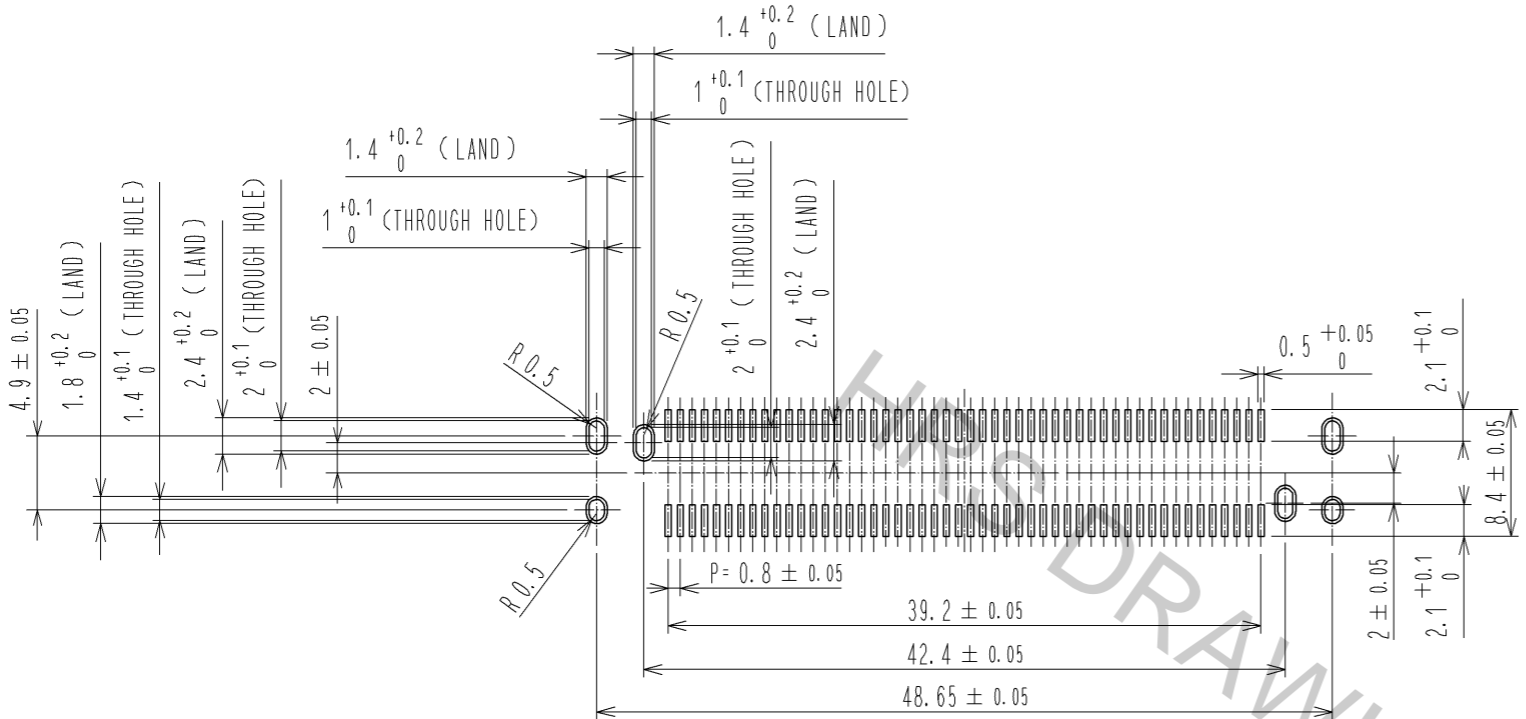
6. BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.

7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

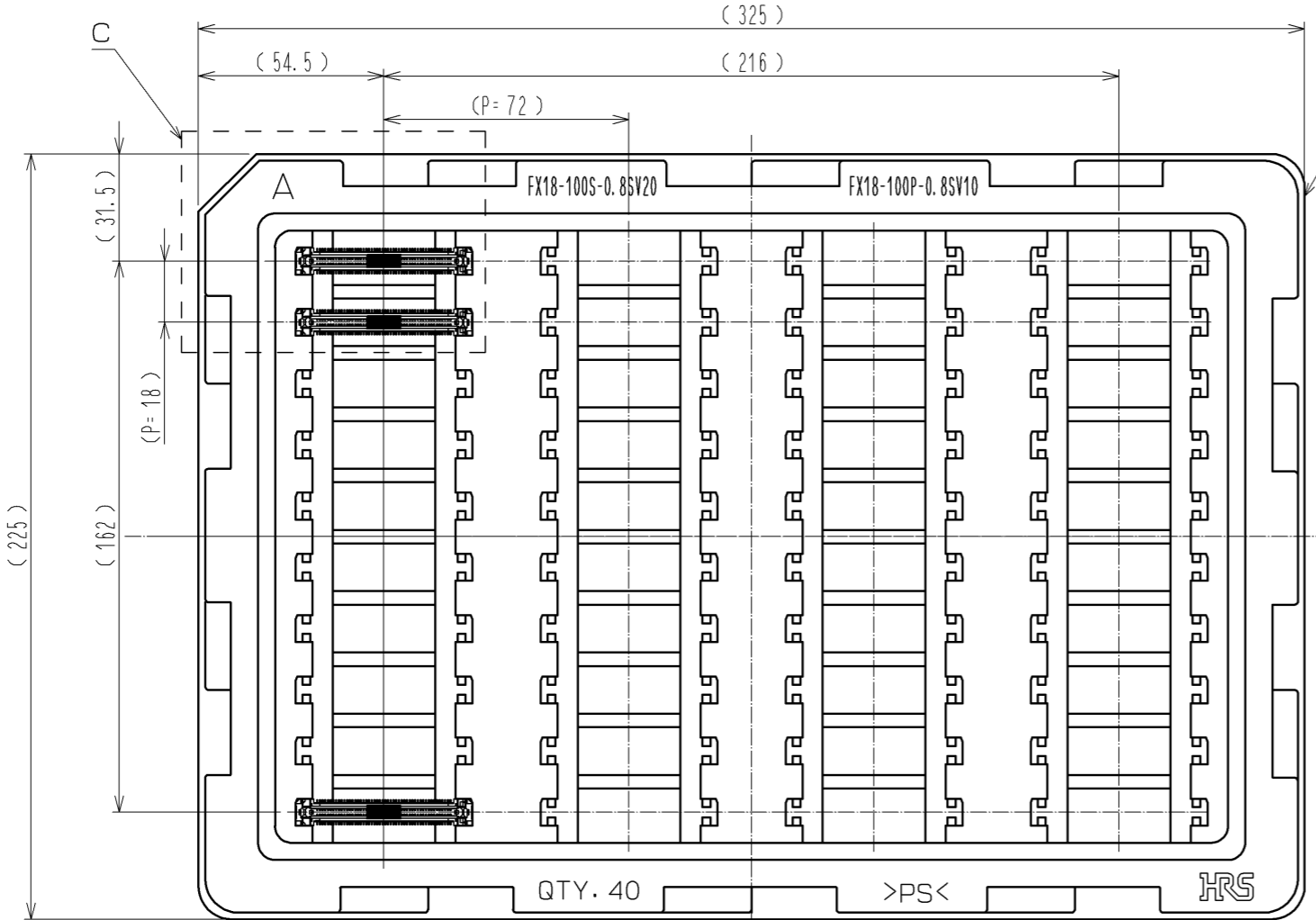
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	5	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm	
		LEAD AREA:GOLD 0.03 μm			LEAD AREA:TIN-PLATING 1 μm	
		UNDER PLATING:NICKEL 1.3 μm			UNDER PLATING:NICKEL 1.3 μm	
2	POLYAMIDE	BLACK UL94V-0	4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm	
1	POLYAMIDE	BLACK UL94V-0			LEAD AREA:TIN-PLATING 1 μm	
					UNDER PLATING:NICKEL 1.3 μm	
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS

UNITS mm		SCALE 2 : 1		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
<div>HIROSE ELECTRIC CO., LTD.</div>		APPROVED	: HS. OKAWA	12. 06. 12	DRAWING NO. EDC3-343463-00			
		CHECKED	: KI. HIROKAWA	12. 06. 12	PART NO. FX18-100P-0. 8SV10			
		DESIGNED	: AH. EDASHIGE	12. 06. 12	CODE NO. CL579-0034-1-00			
		DRAWN	: AH. EDASHIGE	12. 06. 12				

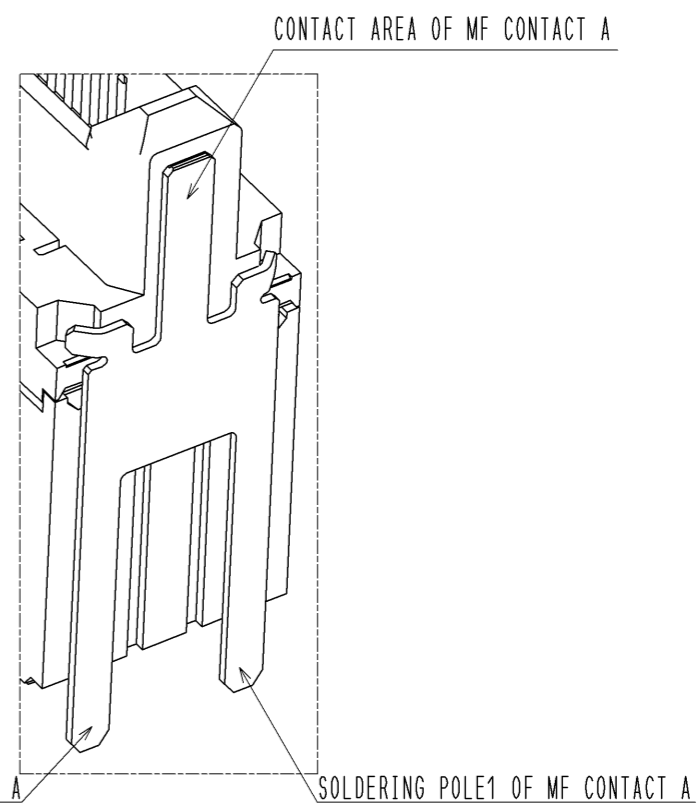
RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)  
(PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)



5 DRAWING FOR PACKING(1:2)

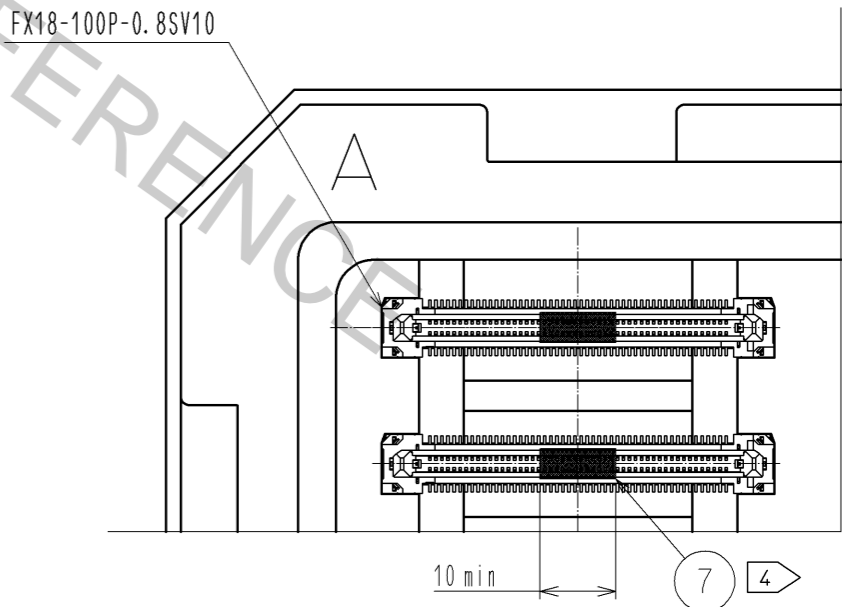


8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.  
BE SURE TO CONNECT TO THE SAME CIRCUIT.

C (1:1)



HRS	DRAWING NO.	EDC3-343463-00
	PART NO.	FX18-100P-0.8SV10
	CODE NO.	CL579-0034-1-00
		△ 2/2